



Material Content Data Sheet



Sales Product Name		IPU50R2K0CE		Issued		2. August 2018		
MA#		MA001839678						
Package		PG-TO251-3-345		Weight*		384.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.070	0.28	0.28	2784	2784
leadframe	inorganic material	phosphorus	7723-14-0	0.063	0.02		163	
	non noble metal	iron	7439-89-6	0.209	0.05		542	
	non noble metal	copper	7440-50-8	208.238	54.17	54.24	541720	542425
	non noble metal	aluminium	7429-90-5	0.138	0.04	0.04	359	359
wire	non noble metal	aluminium	7429-90-5	0.138	0.04	0.04	359	359
encapsulation	organic material	carbon black	1333-86-4	0.706	0.18		1837	
	plastics	epoxy resin	-	19.069	4.96		49607	
	inorganic material	silicondioxide	60676-86-0	121.475	31.60	36.74	316013	367457
leadfinish	non noble metal	tin	7440-31-5	7.055	1.84	1.84	18352	18352
solder	non noble metal	tin	7440-31-5	0.029	0.01		76	
	noble metal	silver	7440-22-4	0.037	0.01		95	
	non noble metal	lead	7439-92-1	1.402	0.36	0.38	3647	3818
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	iron	7439-89-6	0.025	0.01		65	
	non noble metal	copper	7440-50-8	24.879	6.47	6.48	64721	64805
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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